

**IN THE CLAIMS:**

*Please amend the claims as follows.*

1. (Currently Amended) A method of treating an epoxy resin-cured product with a treatment liquid, wherein the liquid contains ~~containing~~ a decomposition catalyst for epoxy resin-cured products and an organic solvent to decompose and dissolve the epoxy resin-cured product, the epoxy resin-cured product contains a halogen atom, and the product is contacted with the liquid to give decomposition products containing a compound recyclable as a raw material of synthetic resins.
2. (Currently Amended) The method according to claim 1, wherein the decomposition catalyst for epoxy resin-cured products contains at least one of ~~or more compounds selected from~~ alkali metals and ~~and/or~~ alkali metal compounds, phosphorous-containing acids and ~~and/or~~ salts thereof, and organic acids ~~salts~~ and ~~and/or~~ salts thereof.
3. (Currently Amended) The method according to claim 1, wherein the organic solvent contains at least one of ~~or more solvents selected from~~ amide-based solvents, alcohol-based solvents, ketone-based solvents, and ether-based solvents.
4. (Original) The method according to claim 2, wherein the alkali metal compounds are alkali metal salts.

5. (Original) The method according to claim 2, wherein the salts of phosphorous-containing acids are hydrates and/or alkali metal salts.
6. (Original) The method according to claim 2, wherein the salts of organic acids are hydrates and/or alkali metal salts.
7. (Cancelled)
8. (Cancelled)
9. (Original) The method according to claim 1, wherein the epoxy resin-cured product is treated under atmospheric pressure.
10. (Original) The method according to claim 1, wherein the treatment liquid has a temperature of 250° C or lower in air and 300° C or lower in an inert gas.
11. (Currently Amended) A method of separating a composite material of inorganic matter and epoxy resin-cured product, comprising ~~the steps of~~:
  - (1) treating the composite material of inorganic matter and epoxy resin-cured product with a treatment liquid containing a decomposition catalyst for epoxy resin-cured products and an organic solvent to decompose and dissolve the epoxy resin-cured product, wherein the composite material is contacted with the liquid; and
  - (2) separating the inorganic matter from the liquid contacted with the composite material obtained in the step (1).

12. (Currently Amended) The method according to claim 11, wherein the decomposition catalyst for epoxy resin-cured products contains at least one of ~~or more compounds selected from~~ alkali metals and ~~and/or~~ alkali metal compounds, phosphorous-containing acids and ~~and/or~~ salts thereof, and organic acids ~~salts~~ and ~~and/or~~ salts thereof.

13. (Currently Amended) The method according to claim 11, wherein the organic solvent contains at least one of ~~or more solvents selected from~~ amide-based solvents, alcohol-based solvents, ketone-based solvents, and ether-based solvents.

14. (Original) The method according to claim 12, wherein the alkali metal compounds are alkali metal salts.

15. (Original) The method according to claim 12, wherein the salts of phosphorous-containing acids are hydrates and/or alkali metal salts.

16. (Original) The method according to claim 12, wherein the salts of organic acids are hydrates and/or alkali metal salts.

17. (Original) The method according to claim 11, wherein the epoxy resin-cured product contains a halogen atom.

18. (Original) The method according to claim 11, wherein the inorganic matter is metal and/or glass.

19. (Currently Amended) The method according to claim 11, wherein the composite material of inorganic matter and epoxy resin-cured product is at least one of an insulating board, a metal-clad laminate, and a printed wiring board.
20. (Original) The method according claim 11, wherein a decomposition product of the epoxy resin-cured product contains a compound recyclable as a raw material of synthetic resins.
21. (Original) The method according to claim 11, wherein the epoxy resin-cured product is treated under atmospheric pressure in the step (1).
22. (Original) The method according to claim 11, wherein the treatment liquid in the step (1) has a temperature of 250° C or lower in air and 300° C or lower in an inert gas.
23. (Currently Amended) A treatment liquid for an epoxy resin-cured product containing a decomposition catalyst for epoxy resin-cured products and an organic solvent, wherein the epoxy resin-cured product contains a halogen atom.
24. (Currently Amended) The treatment liquid according to claim 23, wherein the decomposition catalyst for epoxy resin-cured products contains at least one of ~~or more compounds selected from~~ alkali metals and ~~and/or~~ alkali metal compounds, phosphorous-containing acids and ~~and/or~~ salts thereof, and organic acids ~~salts~~ and ~~and/or~~ salts thereof.

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25. (Currently Amended) The treatment liquid according to claim 23, wherein the organic solvent contains at least one ~~of or more solvents selected from~~ amide-based solvents, alcohol-based solvents, ketone-based solvents, and ether-based solvents.